

31046 U.S. PRO
10/032941
10/31/01

764-905

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10032941	FILING DATE 10/31/2001	CLASS 438	SUBCLASS 939	CAII 3842	EXAMINER <i>Edelotec</i>
----------------------	---------------------------	--------------	-----------------	--------------	-----------------------------

**APPLICANTS: Hedler Harry; Meyer Thorsten; Vasquez Barbara;

S. Clark

**CONTINUING DATA VERIFIED:

BEST AVAILABLE COPY

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO 13292-007001 / 2001P15322
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials			
TITLE : Compliant relief wafer level packaging			

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
Amount Due		Sheets Drwg.	Figs. Drwg.
Date Paid		Print Fig.	
Primary Examiner		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.			

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
(Attached in pocket on right inside flap)